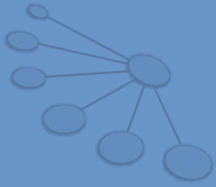


On Reliability of Microelectronic Devices: An Introductory Lecture on Negative Bias Temperature Instability

M. A. Alam

Purdue University
West Lafayette, IN

Sept. 28, 2005



Reliability has always been Important!

Reliability has always been Important!

A 5000 year old example:

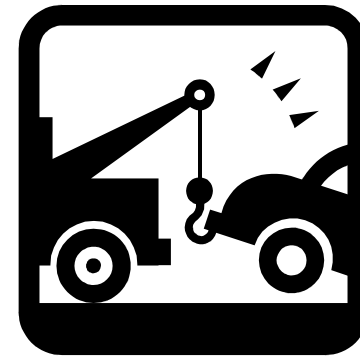
Stone vs. Copper tools

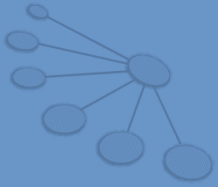


A modern example:

Honda vs. Yugo

“The car is named Yugo, because it doesn’t ...”





Microelectronics reliability & viable technologies

□ Pauli to his student Peierls, in 1932, on unreliability of Cu_2S , Ag_2S :

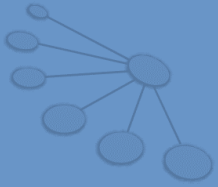
“Do not work on semiconductors, it is a mess (eine schweinerei); who knows if semiconductor exists at all”

□ Kelly (Bell Labs) to recently-hired Shockley in 1936:

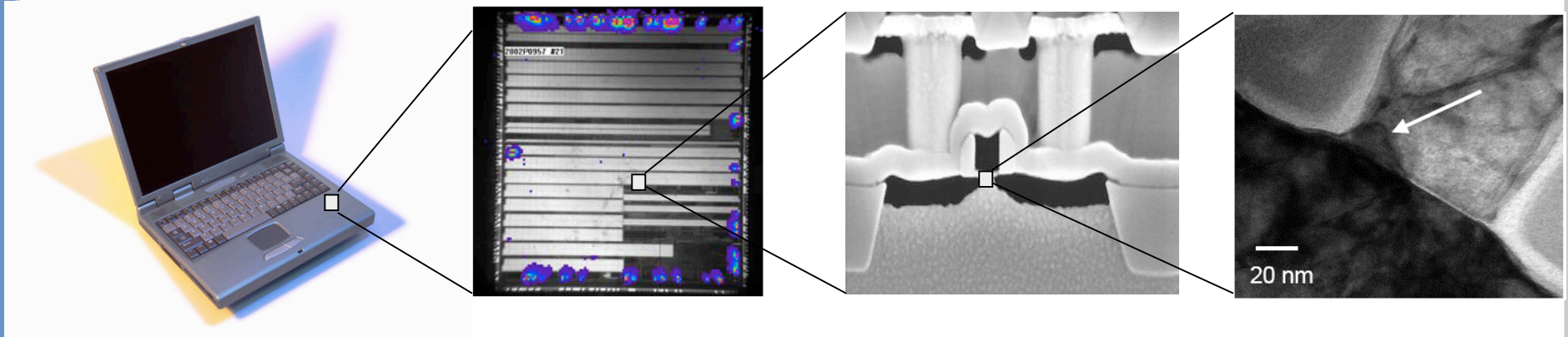
“Instead of mechanical devices, which has annoying maintenance problem, we should look for (reliable) solid state switch”

□ Landauer on quantum computing (1992):

“.... this proposal depends on speculative technology, does not in its current form account all possible sources of noise, unreliability, and manufacturing error, and probably will not work.”



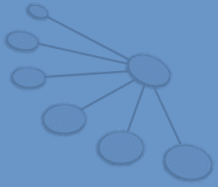
Warranty, Product Recall, and Other Facts of Life



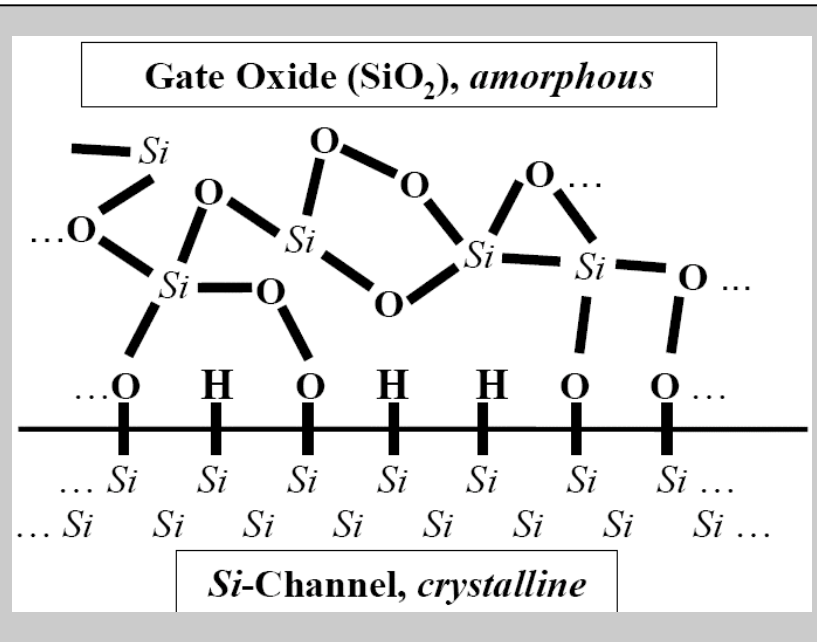
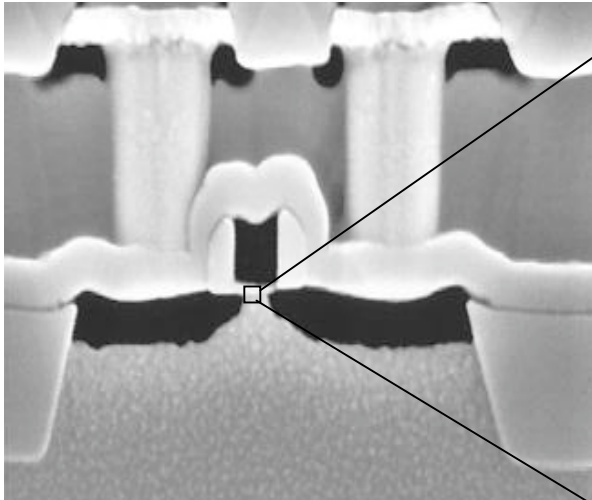
A manufacturer bets
the company of the
physics of reliability

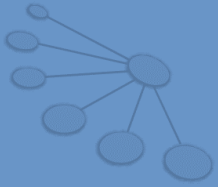
... because the ICs
operate in incredibly
harsh conditions, turning
on and off trillions of time
during its lifetime

... because the lines could
open, the source/drain
can be shorted, the gate
oxide can break



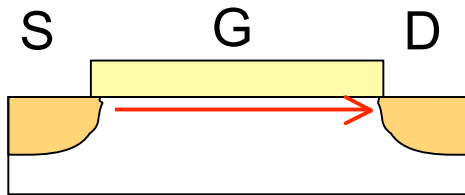
Si-H and SiO₂ Bonds



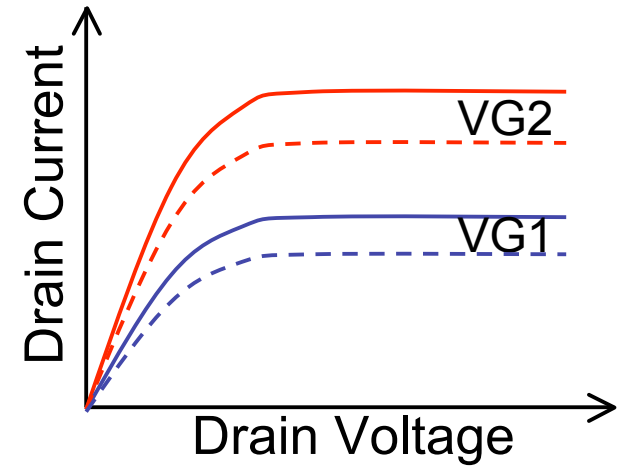
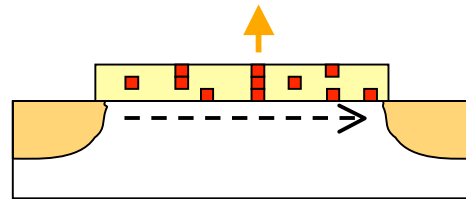


Reliability Issues in Modern Transistors

Initially



.... a few months later

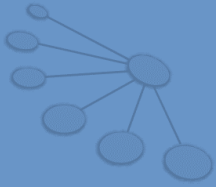


Broken Si-H bonds:

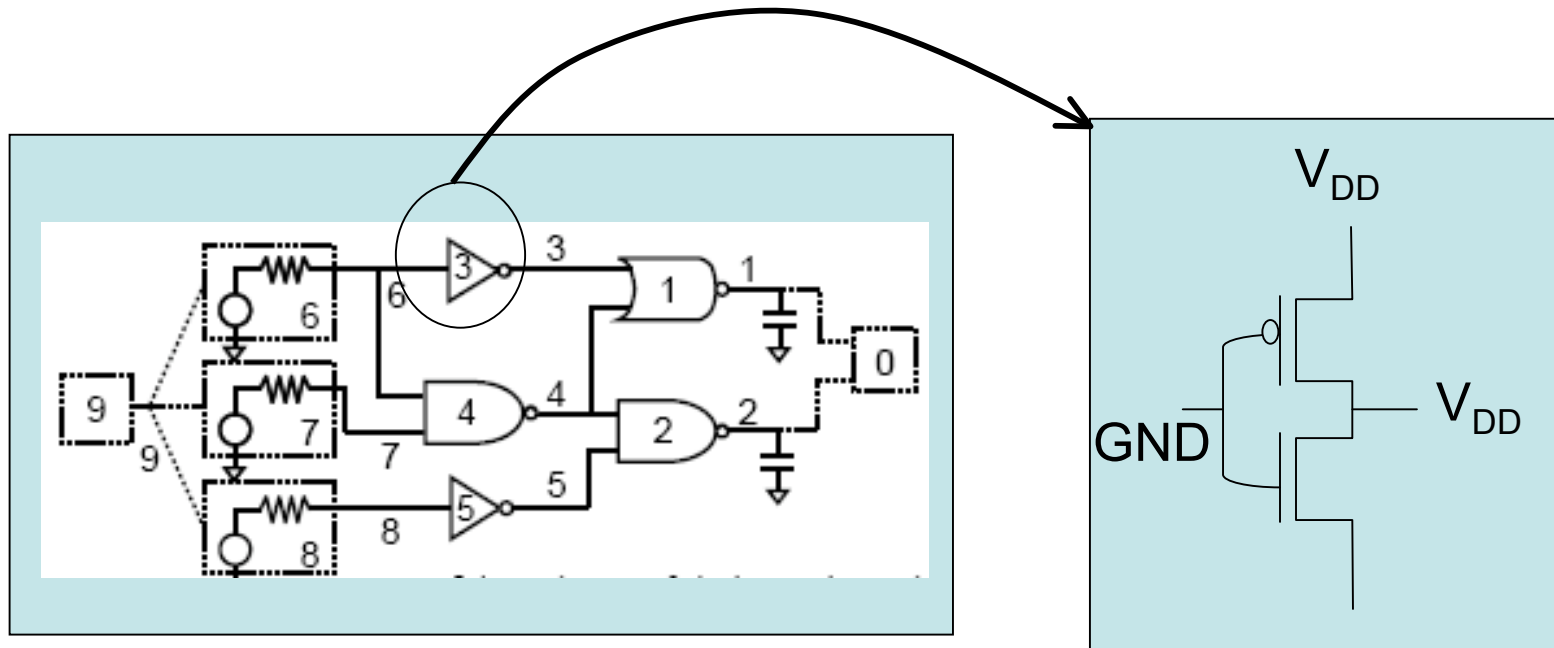
Negative Bias Temperature Instability (NBTI)
Hot carrier degradation (HCI)

Broken Si-O bonds:

Gate dielectric Breakdown (TDDB)



Introduction: NBTI defined

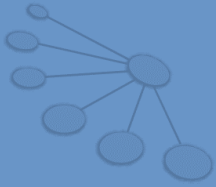


NBTI: **N**egative **B**ias **T**emperature **I**nstability

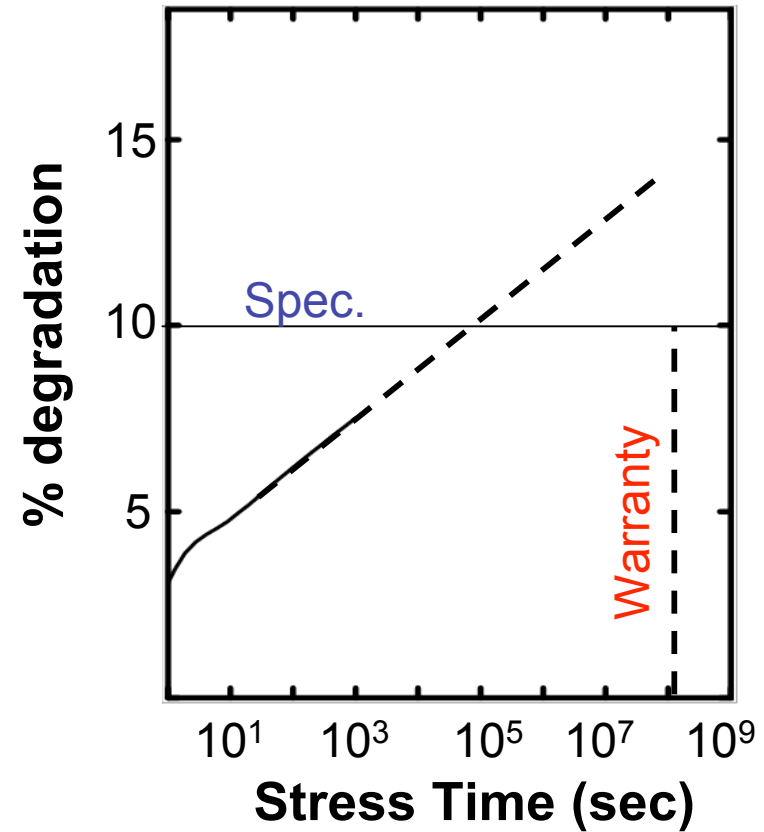
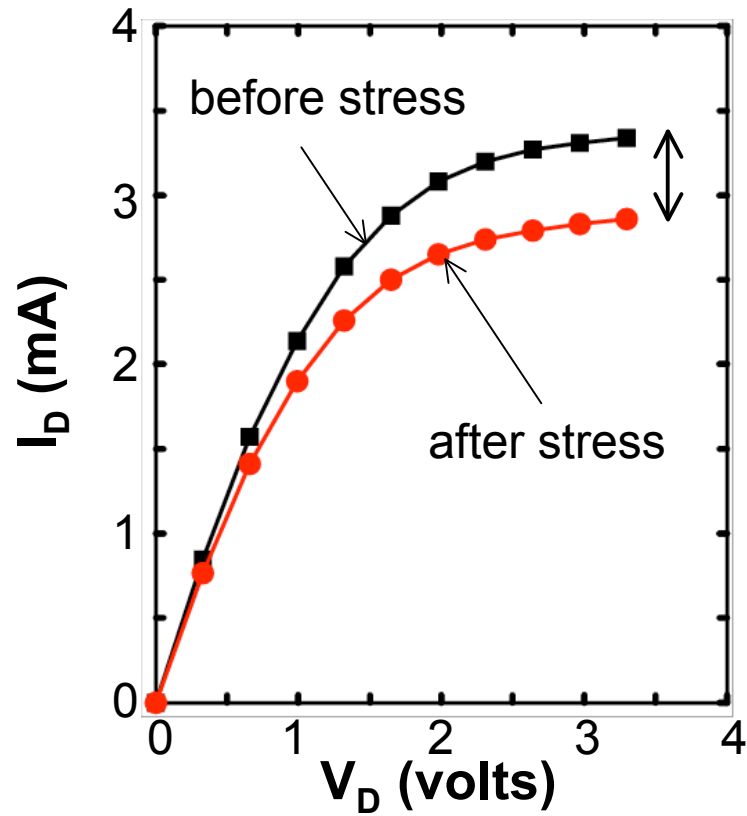
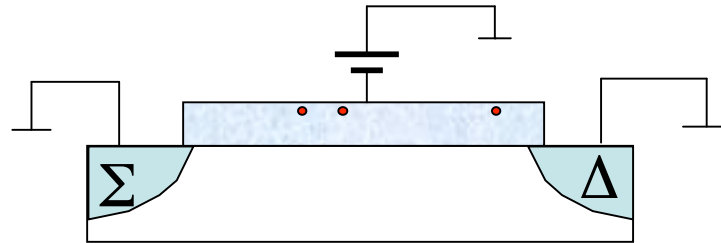
Gate: GND, **Drain:** VDD, **Source:** VDD

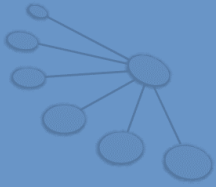
Gate negative with respect to S/D

Other degradation modes: TDDB, HCI, etc.



NBTI & Parametric Failure





A Brief History of NBTI

Experiments in late 1960s by Deal and Grove at Fairchild

- Role of Si-H bonds and BTI vs. NBTI story (J. Electrochem Soc. 1973;114:266)
- Came out naturally as PMOS was dominant
- Important in FAMOS and p-MNOS EEPROMS (Solid State Ckts 1971;6:301)

Theory in late 1970s by Jeppson (JAP, 1977;48:2004)

- Generalized Reaction-Diffusion Model
- Discusses the role of relaxation, bulk traps,
- Comprehensive study of available experiments

Early 1980s

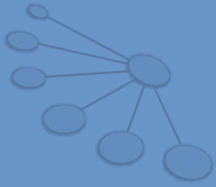
- Issue disappears with NMOS technology and buried channel PMOS

Late 1980s and Early 1990s

- Begins to become an issue with dual poly gate, but HCI dominates device reliability

Late 1990s/Early 2000 (Kimizuka, IRPS97;282. Yamamoto, TED99;46:921. Mitani, IEDM02;509)

- Voltage scaling reduces HCI and TDDB, but increasing field & temperature reintroduce NBTI concerns for both analog and digital circuits
- Numerical solution is extensively used for theoretical modeling of NBTI.

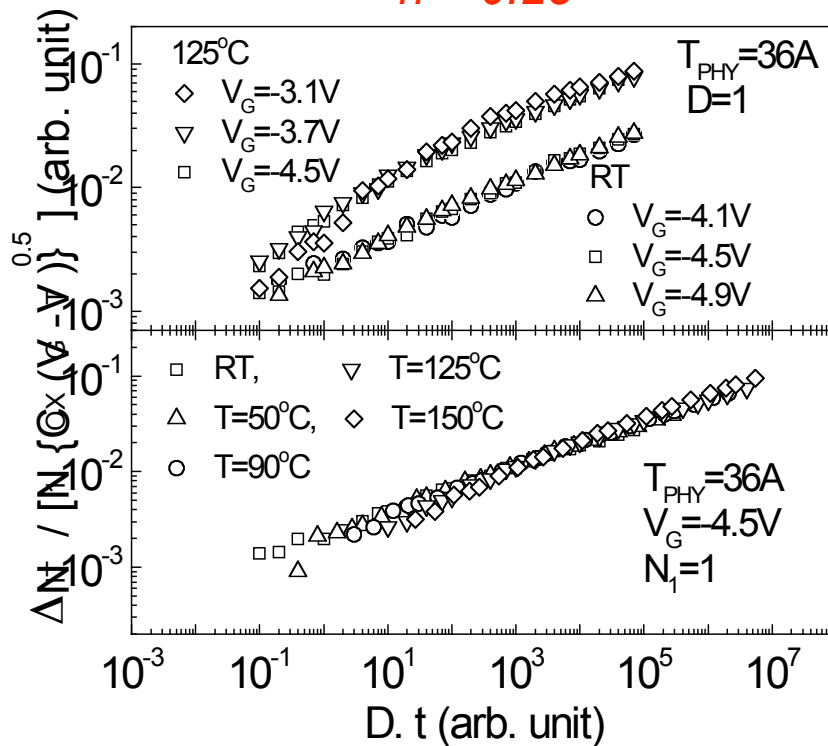


Exponent and Activation

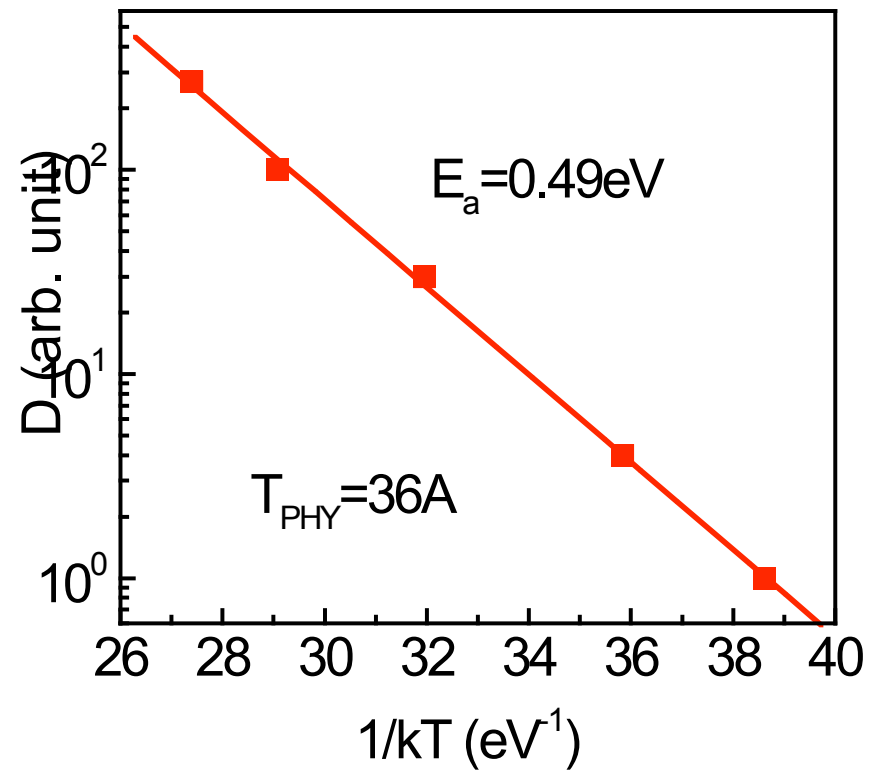
$$N_{IT}(t) = A e^{-Ea/k_B T} t^n$$

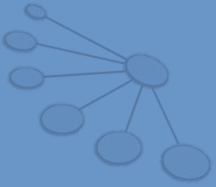
$$\log(N_{IT}(t)) = n \log(t) + (\log(A) - Ea/k_B T)$$

$n \sim 0.25$

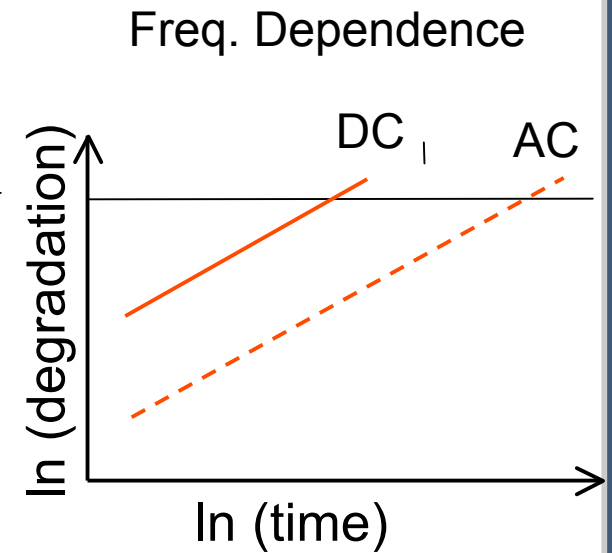
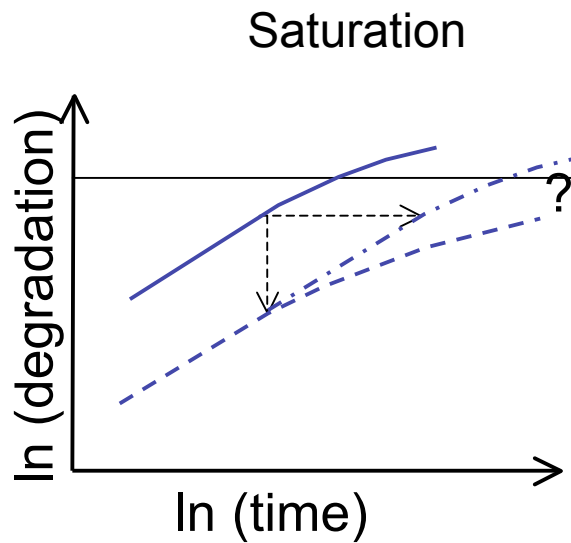
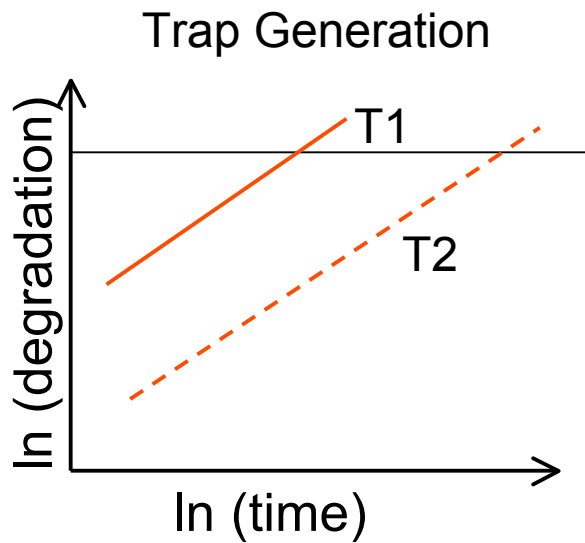


$Ea \sim 0.5$



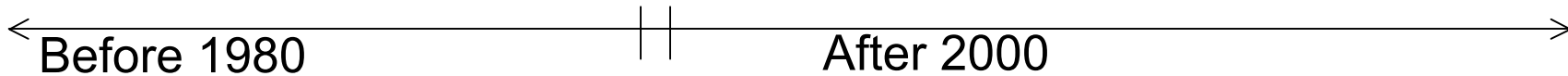


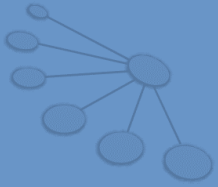
A 40-year-old Puzzle ...



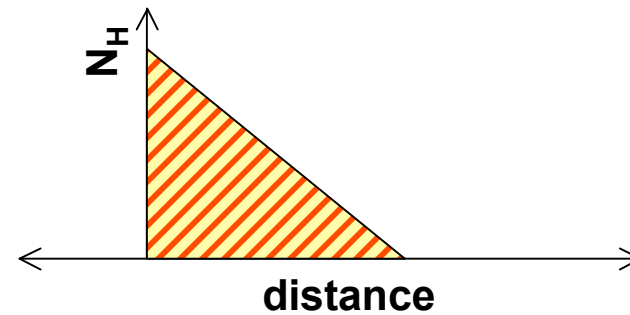
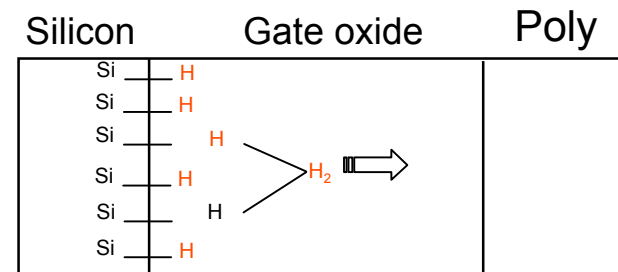
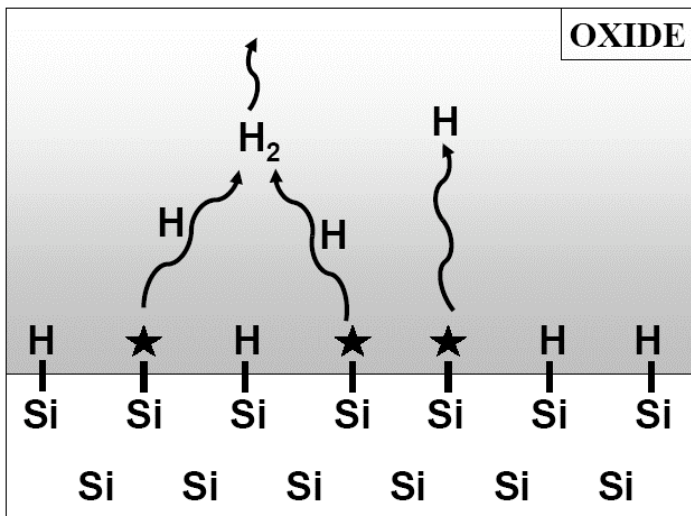
- $n=0.25$ (H diffusion ?)
- $E_A=0.5$ (H_2 diffusion ?)

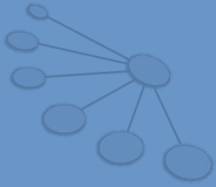
- The exponent is soft ($n_{sat} = 0.16$) !
- NBTI depends on frequency.



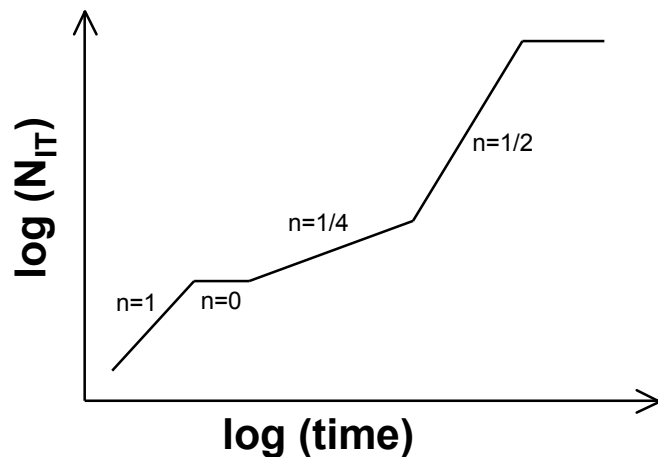
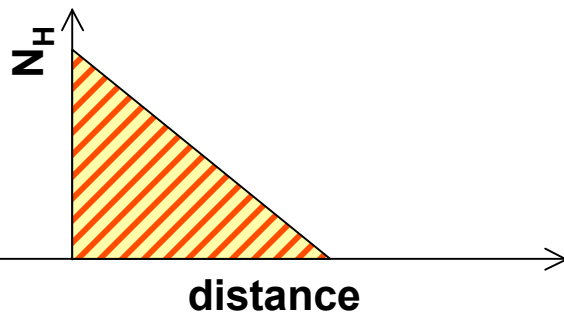
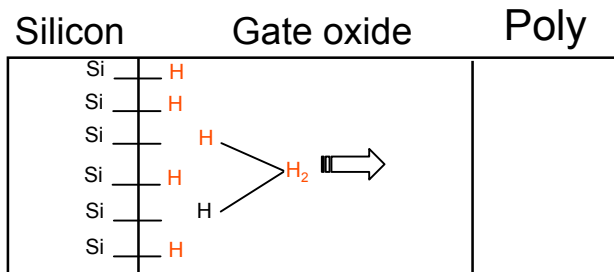


A Word about Drawings





The Reaction-Diffusion Model



$$\frac{dN_{IT}}{dt} = k_F(N_0 - N_{IT}) - k_R N_H(0) N_{IT}$$

k_F : Si-H dissociation rate const.

Creates broken-bond N_{IT}

k_R : Rate of reverse annealing of Si-H

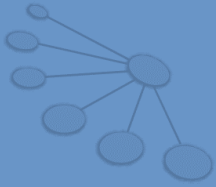
N_0 : Total number of Si-H bonds

$$\frac{dN_H}{dt} = D_H \frac{d^2 N_H}{dt^2} + N_H \mu_H E + \frac{\delta}{2} \frac{dN_{IT}}{dt}$$

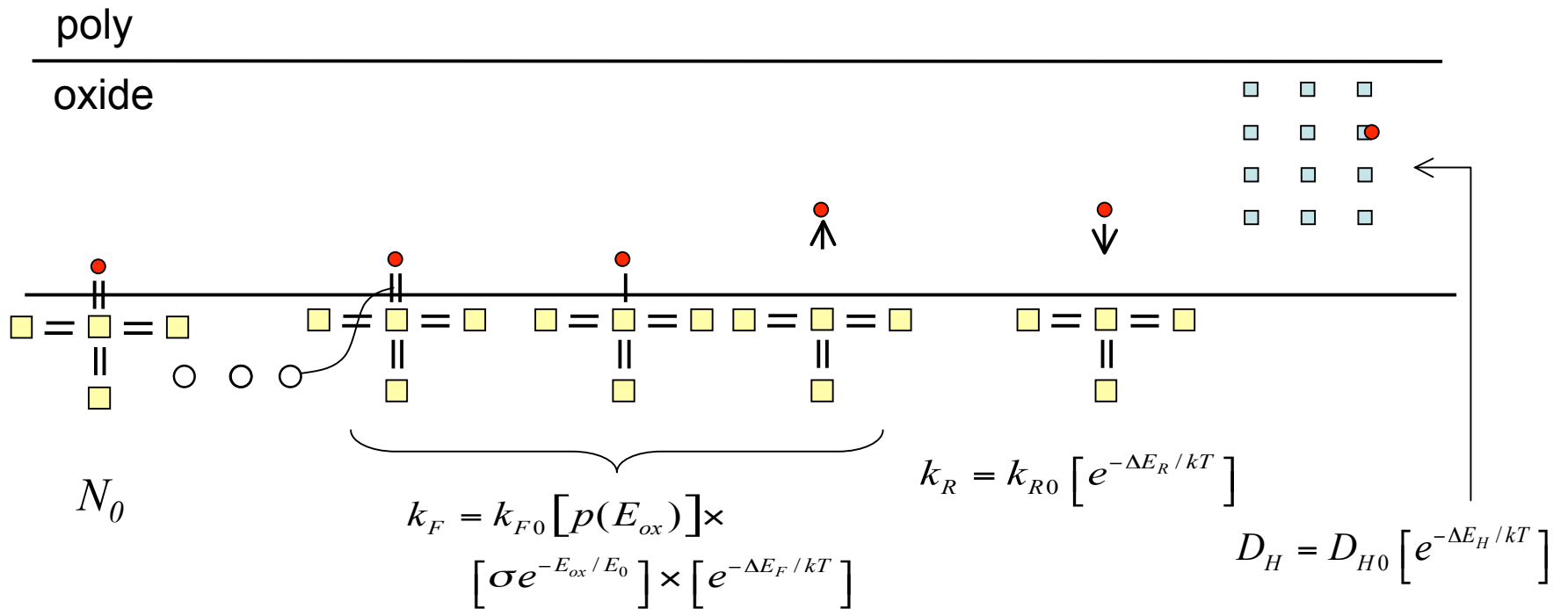
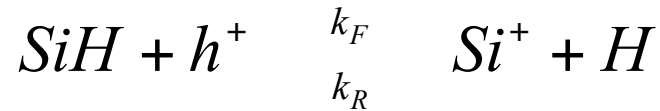
N_H : Hydrogen density

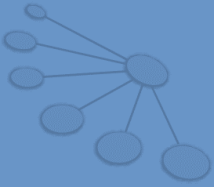
D_H : Hydrogen diffusion coefficient

μ_H : Hydrogen mobility

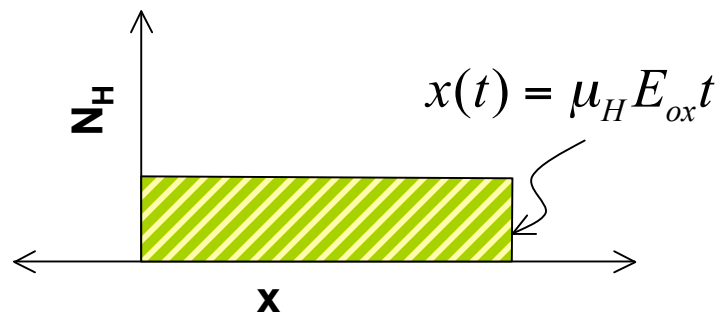
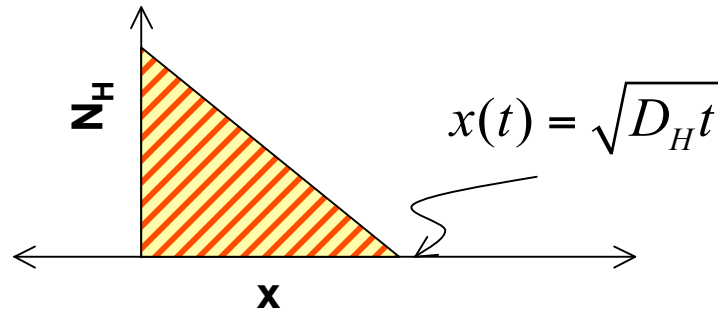
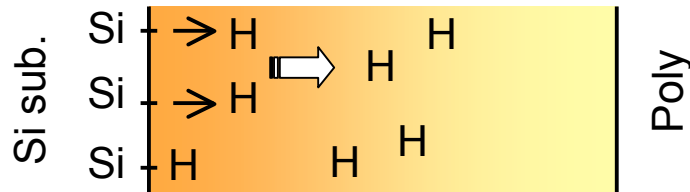


Meaning of the Parameters





A Reformulation of R-D Model



$$\frac{dN_{IT}}{dt} = k_F (N_0 - N_{IT}) - k_R N_H(0) N_{IT}$$

If trap generation rate is small,
and if N_{IT} much smaller than N_0 , then

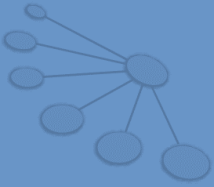
$$\left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

$$\frac{dN_{IT}}{dt} = D_H \frac{d^2 N_H}{dx^2} + N_H \mu_H E + \frac{\delta}{2} \frac{dN_H}{dt}$$

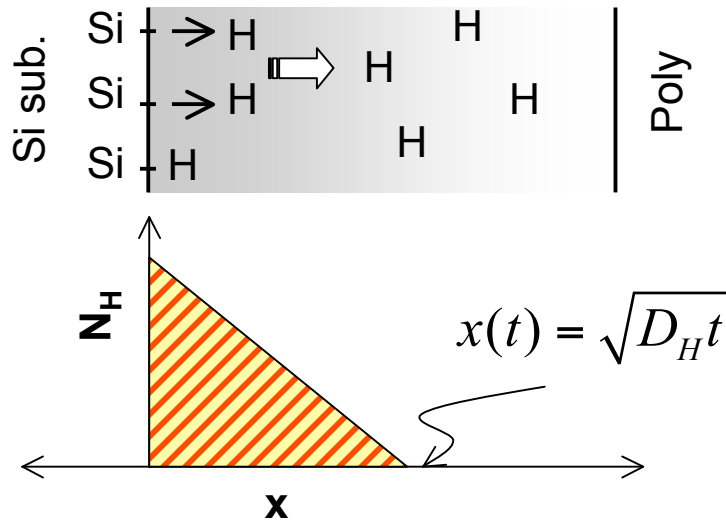
$$N_{IT}(t) = \int_{x=0}^{x(t)=f(D_H, \mu_H, t)} N_H(x, t) dx$$

$$N_{IT}(t) = \int_0^{\sqrt{D_H t}} N_H(x, t) dx \quad (\text{Neutral})$$

$$N_{IT}(t) = \int_0^{\mu_H E_{ox} t} N_H(x, t) dx \quad (\text{Charged})$$



NIT with Neutral H Diffusion



$$\left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

$$N_{IT}(t) = \int_0^{\sqrt{D_H t}} N_H(x, t) dx$$

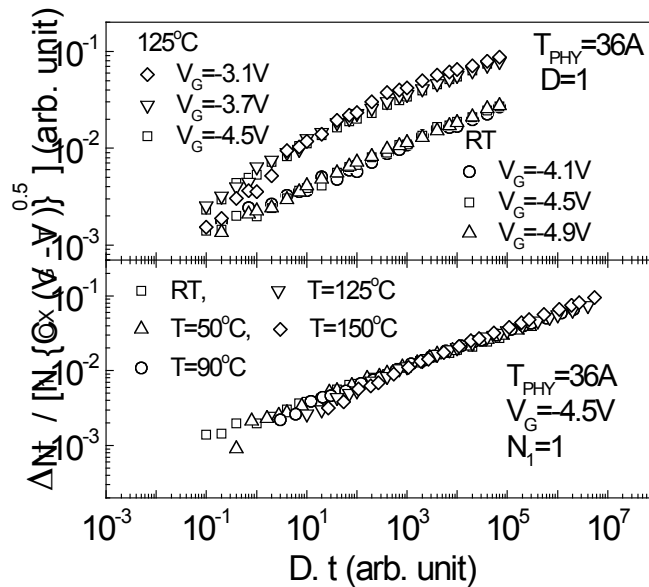
$$= \frac{1}{2} N_H(0) \sqrt{D_H t}$$

Combining these two, we get

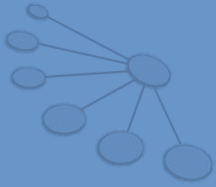
$$N_{IT}(t) = \sqrt{\frac{k_F N_0}{2k_R}} (D_H t)^{1/4}$$

$n=1/4$ even with two sided diffusion

$n \sim 1/4$ is a possible signature of neutral H diffusion



Reproduces results of Jeppson, JAP, 1977.



NIT with Neutral H₂ Diffusion

$$\left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

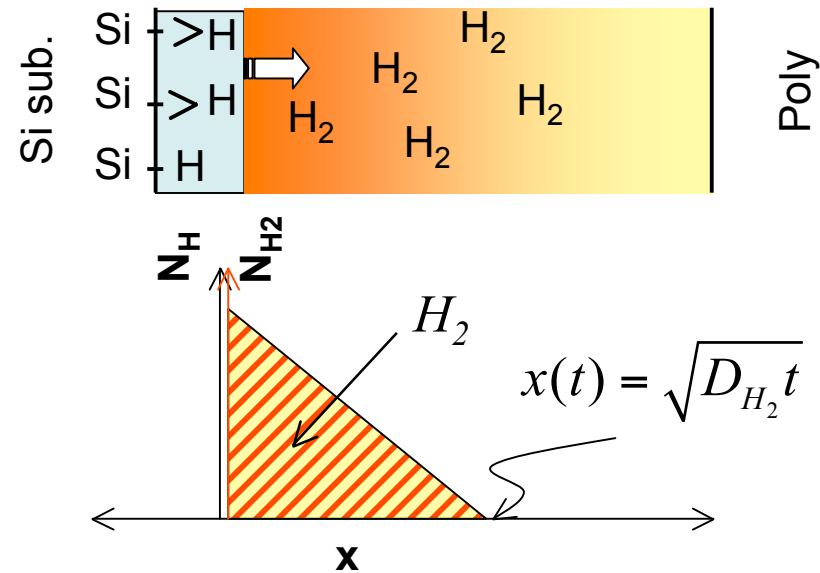
$$N_{IT}(t) = \int_0^{\sqrt{D_{H_2} t}} N_H(x, t) dx$$

$$= \frac{1}{2} N_{H_2}(0) \sqrt{D_{H_2} t}$$

$$const. = \frac{N_H(0)^2}{N_{H_2}(0)} \quad (2H \quad H_2)$$

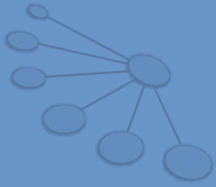
Combining these two, we get

$$N_{IT}(t) \propto \sqrt{\frac{k_F N_0}{2k_R}} (D_{H_2} t)^{1/6}$$



- $n \sim 1/6$ is a possible signature of neutral H₂ diffusion
- Small exponent because generation is more difficult.

Reproduces results of Chakravarthi, IRPS, 2003.



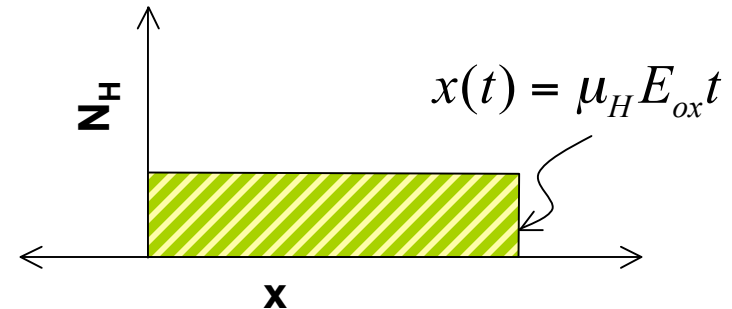
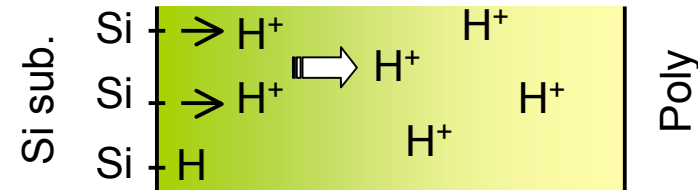
NIT with charged H⁺ Drift

$$\left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

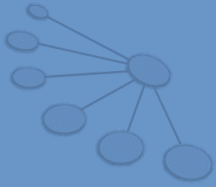
$$\begin{aligned} N_{IT}(t) &= \int_0^{\mu_H E_{ox} t} N_H(x, t) dx \\ &= \frac{1}{2} N_H(0) \mu_H E_{ox} t \end{aligned}$$

Combining these two, we get

$$N_{IT}(t) = \sqrt{\frac{k_F N_0}{2k_R}} (\mu_H E_{ox} t)^{1/2}$$



- $n \sim 1/2$ is a possible signature of charged H diffusion
- Rapid removal of H^+ by E_{ox} field increase N_{IT} gen. rate.



NIT with charge H_2^+ Drift

$$\left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

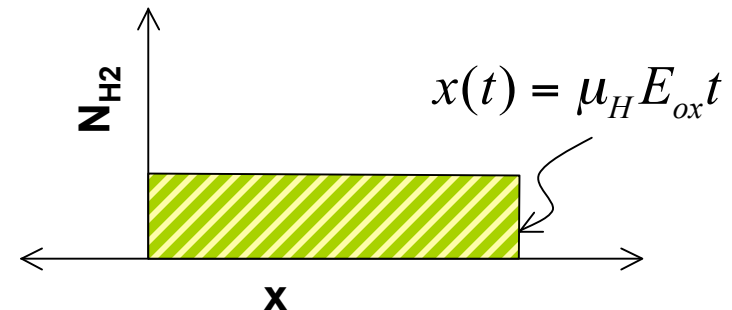
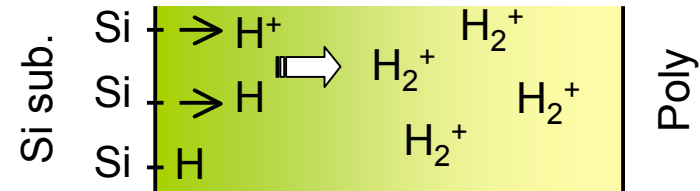
$$N_{IT}(t) = \int_0^{\mu_H E_{ox} t} N_{H_2}(x, t) dx$$

$$= \frac{1}{2} N_{H_2}(0) \mu_H E_{ox} t$$

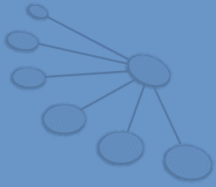
$$const. = \frac{N_H(0)^2}{N_{H_2}(0)} \left(H + H^+ \right) H_2^+$$

Combining these two, we get

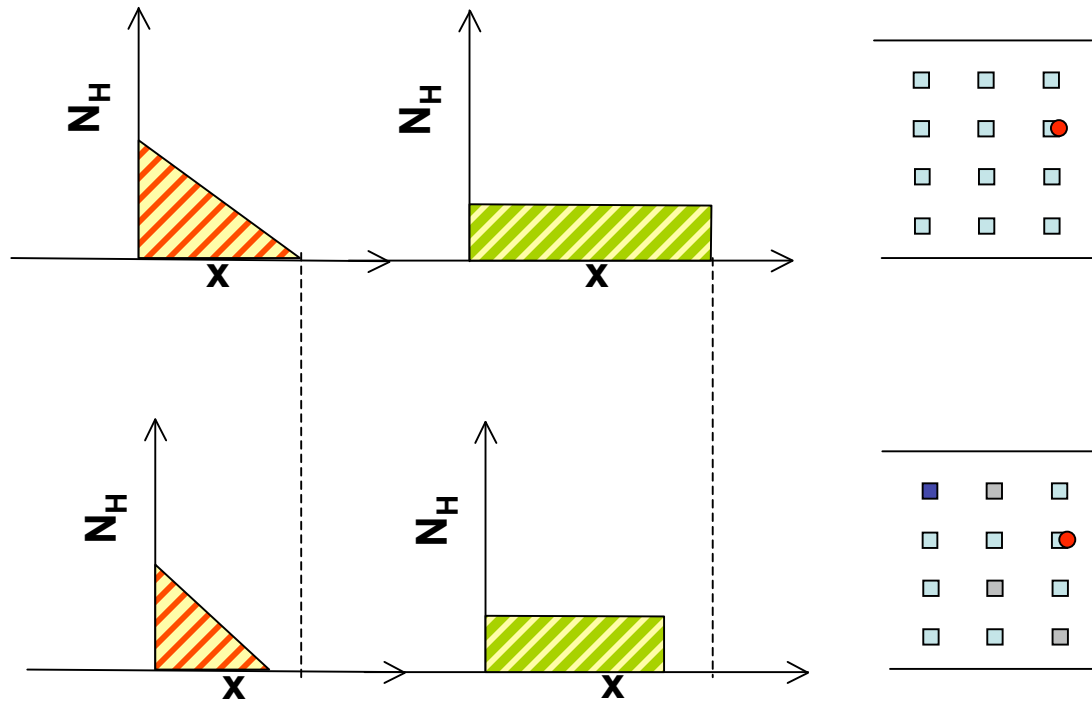
$$N_{IT}(t) \propto \sqrt{\frac{k_F N_0}{2k_R}} (\mu_H E_{ox} t)^{1/3}$$



- $n \sim 1/3$ is a possible signature of charged H_2^+ diffusion
- Exponents above $1/3$ seldom seen in charge-pumping expt. (uncorrelated to SILC).



Dispersive Diffusion & non-rational n



$$N_{IT}(t) \propto \sqrt{\frac{k_F N_0}{2k_R}} (D_{H^*} t)^n$$

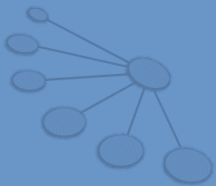
$$D_H = D_0 (\omega_0 t)^{-p}$$

Shkrob, PRB, 1996; 54:15073

$$N_{IT}(t) \propto \sqrt{\frac{k_F N_0}{2k_R}} \left(\frac{D_0}{w^p}\right)^n t^{n(1-p)}$$

- R-D model predicts $n=0.30-0.12$
- More amorphous oxides for better NBTI
- For finite oxides, at very long time all n must be rational (no problem > 10 yrs)

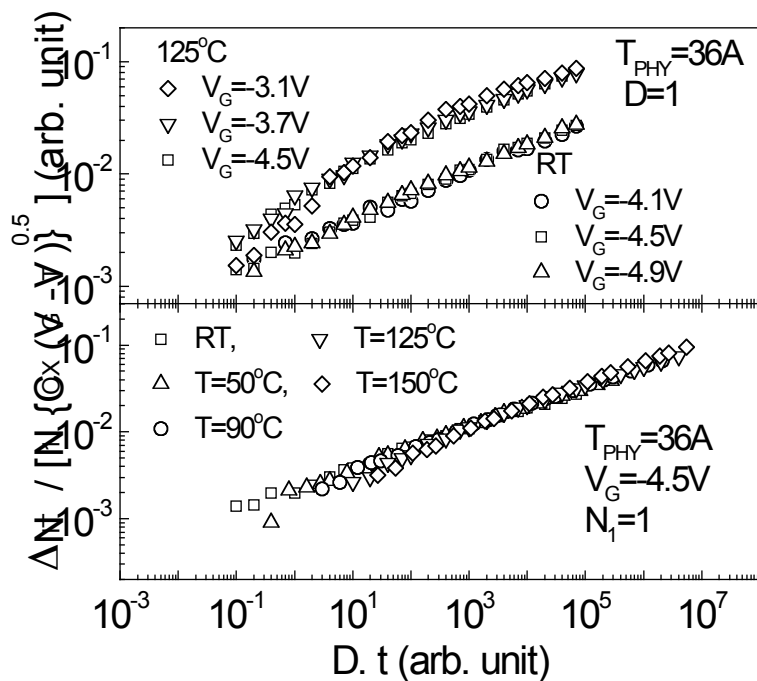
	n_{ideal}	n_{dis}
H	0.25	0.20-0.25
H2	0.16	0.128-0.144
H2+	0.33	0.264-0.297



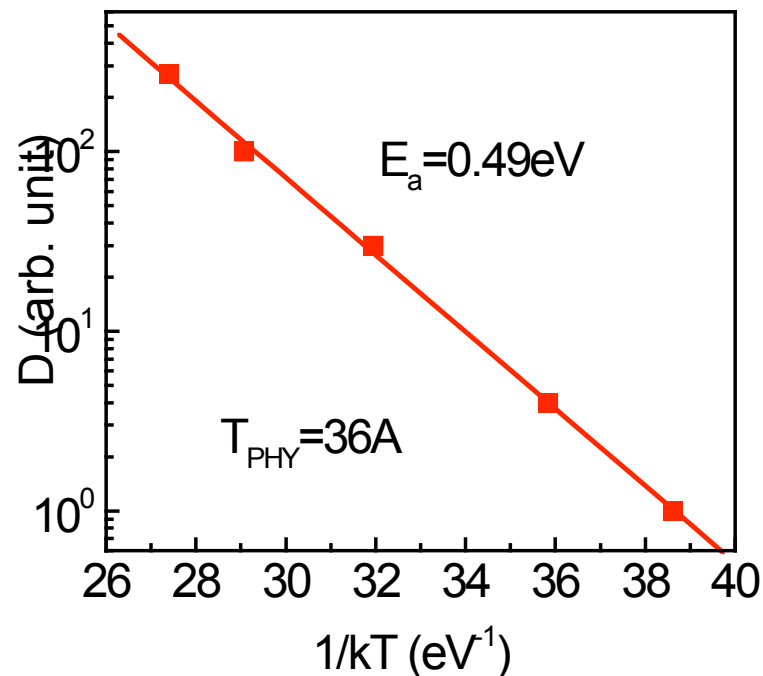
Puzzle: H or H₂ or H₂⁺ ?

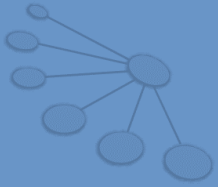
$$N_{IT}(t) = \sqrt{\frac{k_F N_0}{2k_R}} (D_0 e^{-E_a/k_B T} t)^n$$

n ~ 0.25 (H or H₂⁺ diffusion?)

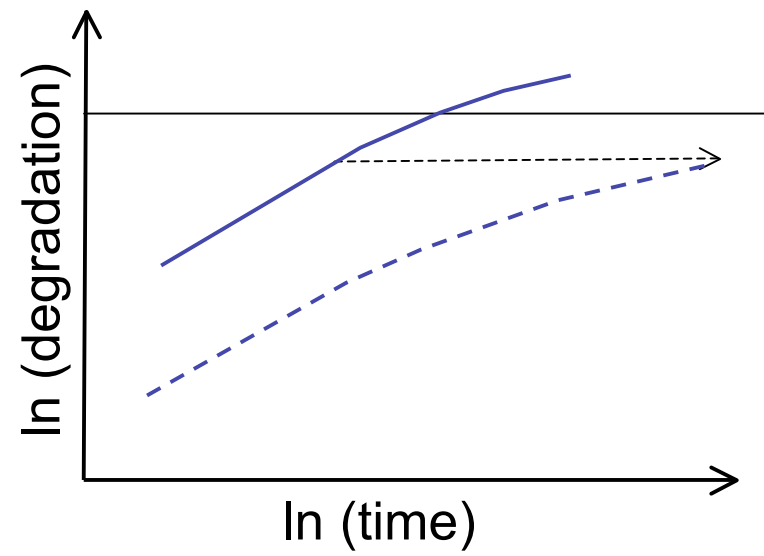


E_a ~ 0.5 (H₂ diffusion ?)

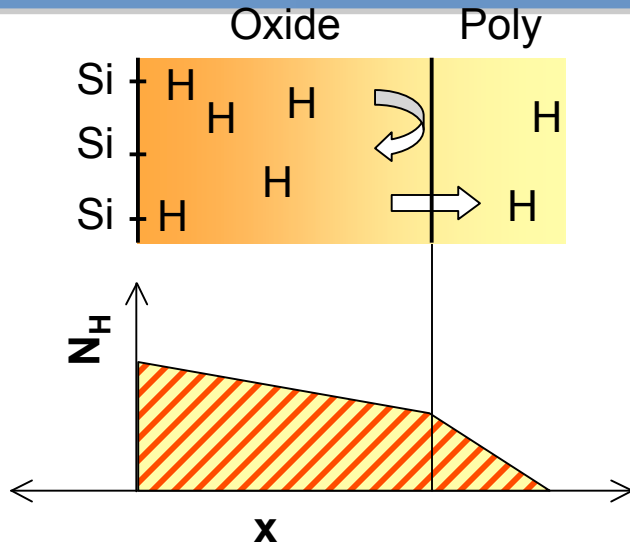




Clue 1: NBTI Saturation



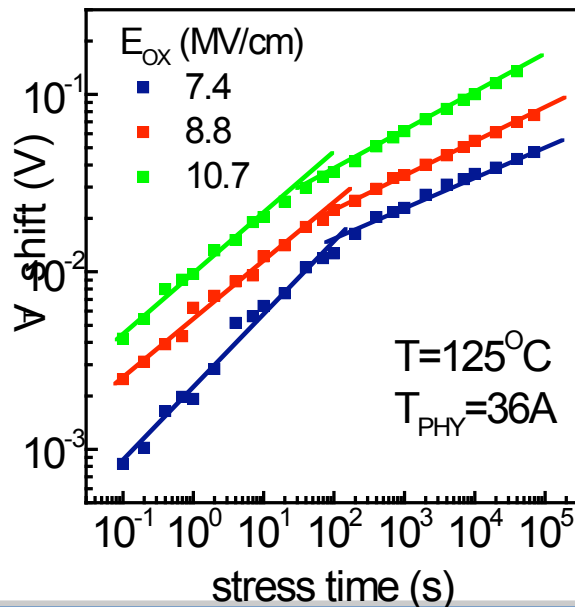
Saturation by Poly Reflection



$$(1) \quad \left(\frac{k_F N_0}{k_R} \right) \approx N_H(0) N_{IT}$$

$$(2) \quad N_{IT}(t) = \frac{1}{2} N_H(T_{ox}) \sqrt{D_H t} + \frac{W}{2} \{N_H(W) + N_H(0)\}$$

$$(3) \quad D_H^{(poly)} \frac{N_H(W)}{\sqrt{D_H^{(poly)} t}} = D_H^{(ox)} \left(\frac{N_H(0) - N_H(W)}{W} \right)$$

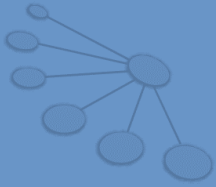


Combining, at short time, we get

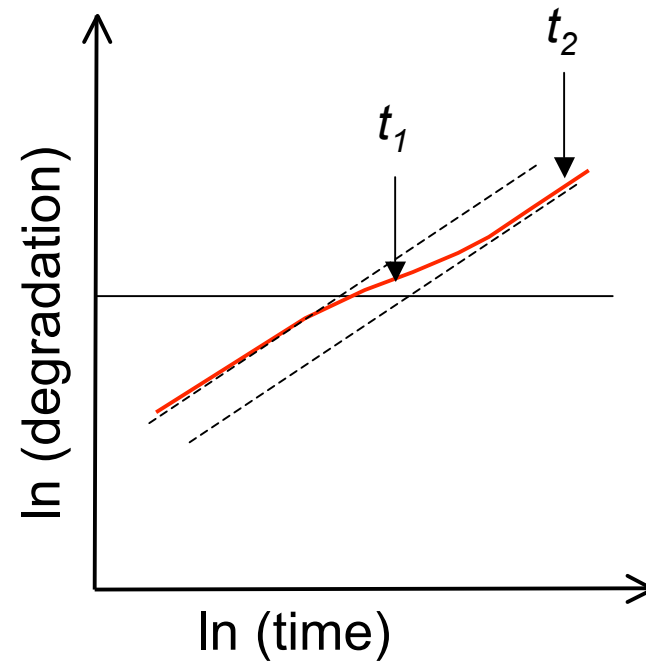
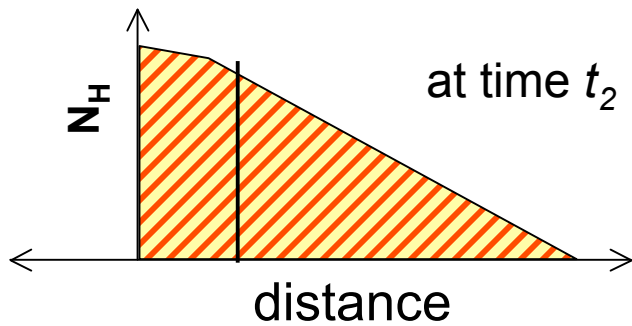
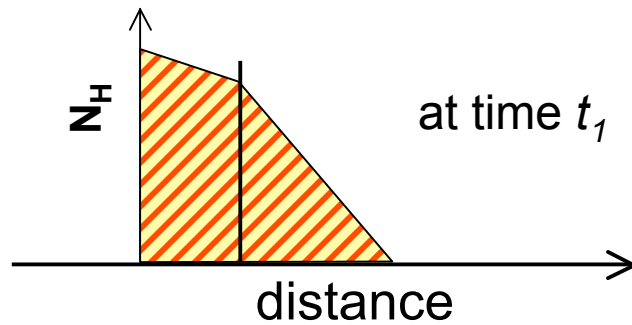
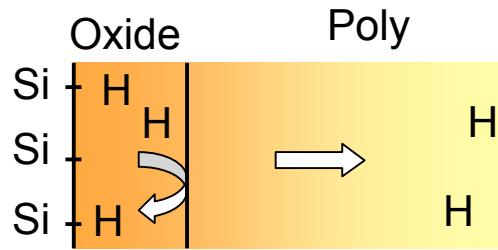
$$N_{IT}(t) \propto \sqrt{\frac{k_F N_0}{2k_R}} \left(\sqrt{D^{(poly)} t} + 2T_{ox} + \frac{T_{ox}^2}{D^{(ox)}} \sqrt{\frac{D_H^{(poly)}}{t}} \right)^{1/2}$$

... but alas, at long time

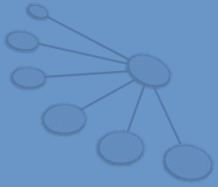
$$N_{IT}(t) \approx \sqrt{\frac{k_F N_0}{2k_R}} \left\{ D_H^{(poly)} t \right\}^{1/4}$$



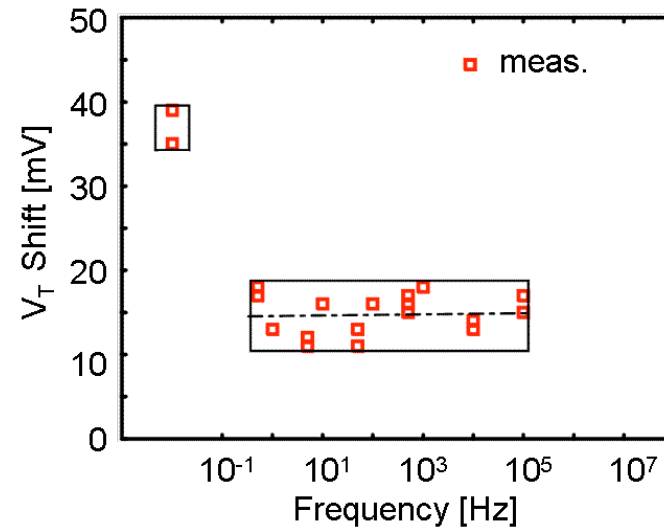
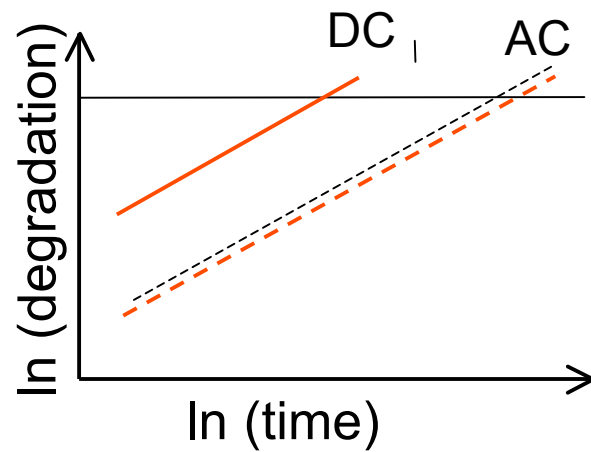
... but the explanation is wrong



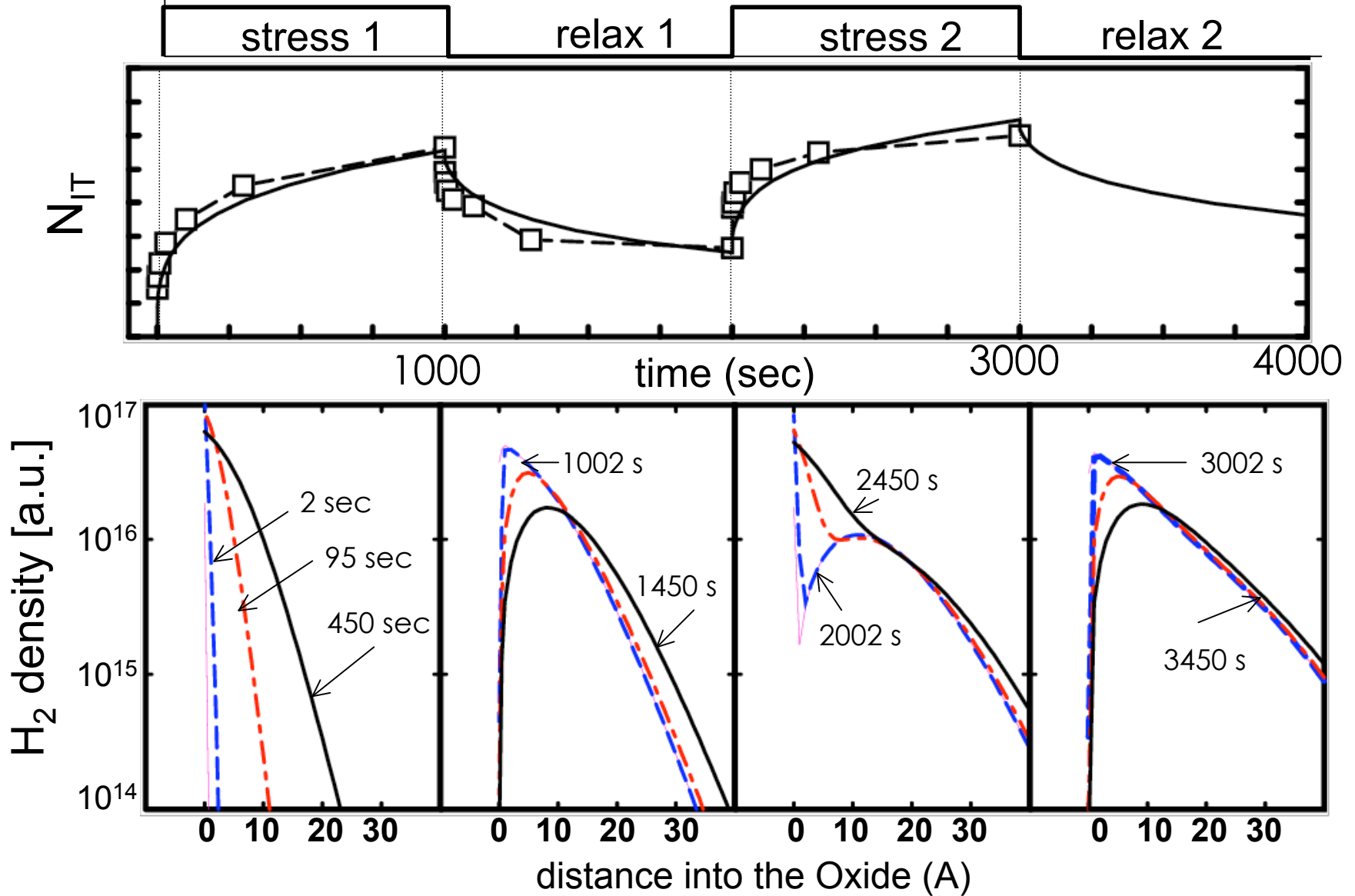
Kufluoglu, unpublished results



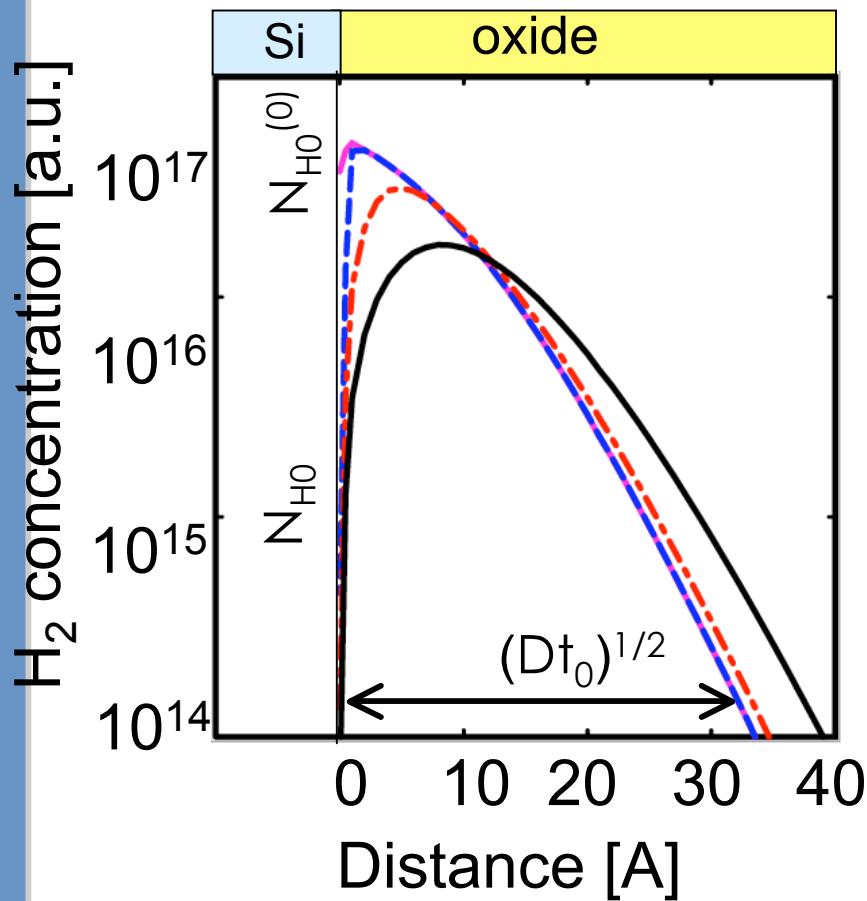
Clue 2: Frequency Dependence



R-D Model at Low Frequencies



Analytical Model: Relaxation Phase



$$N_{IT}^{(0)} = \frac{1}{2} N_H(0) \sqrt{D_H \tau_0}$$

$$N_{IT}^{(*)} = \frac{1}{2} N_H(0) \sqrt{\xi D_H t}$$

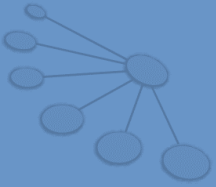
$$\frac{dN_{IT}}{dt} = k_F (N_0 - N_{IT}) - k_R N_H(0) N_{IT}$$

$$N_{H0} = N_{H0}^{(0)} - N_H^{(*)}$$

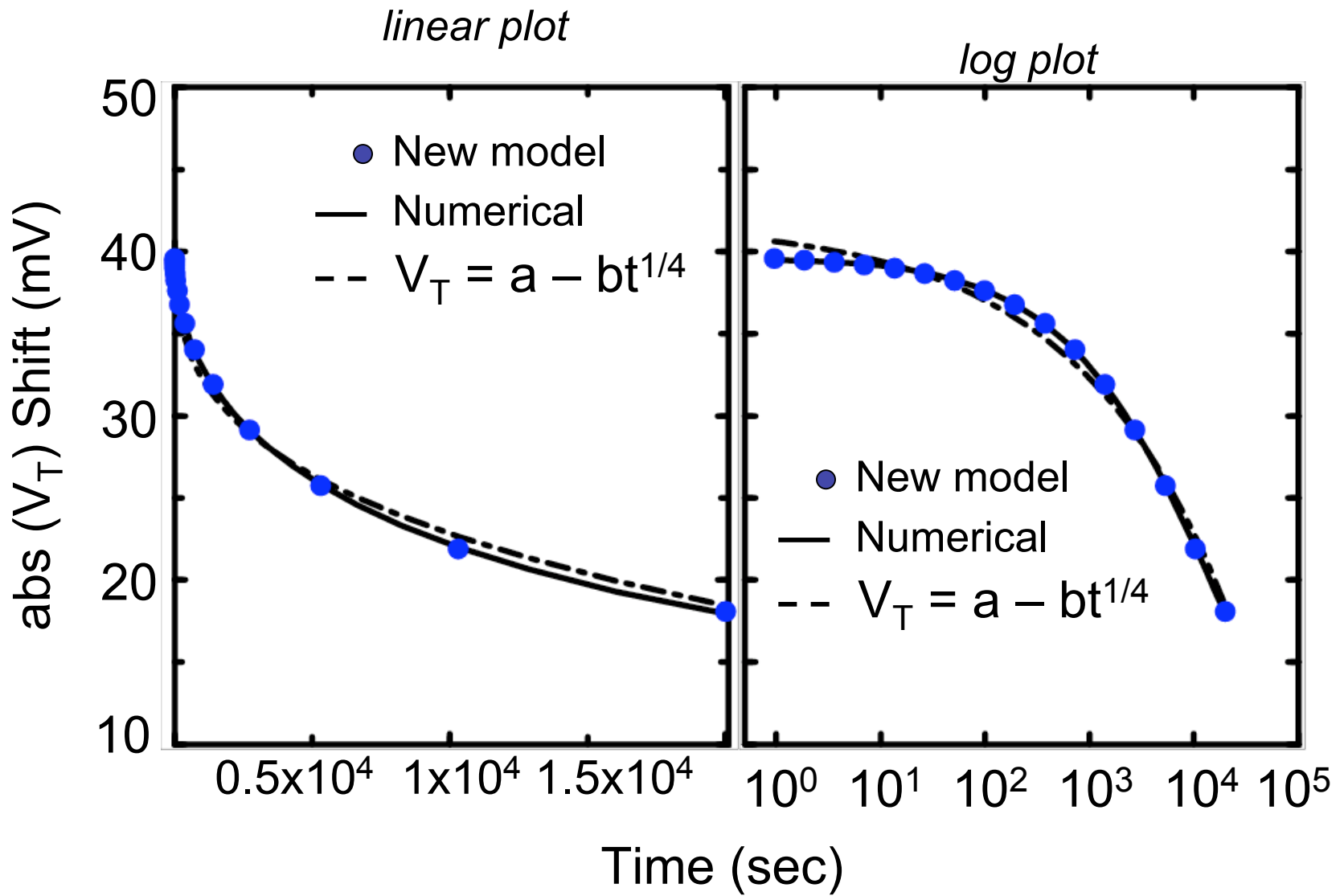
$$N_{IT} = N_{IT}^{(0)} - N_{IT}^{(*)}$$

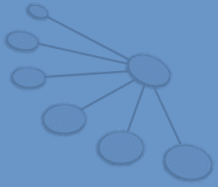
$$AN_{H0}^2 + BN_{H0} + C = 0$$

$$N_{IT} = N_{IT}^{(0)} \left(1 - \sqrt{\frac{\xi x}{1+x}} \right) \quad x \equiv \left(\frac{t}{\tau_0} \right)$$

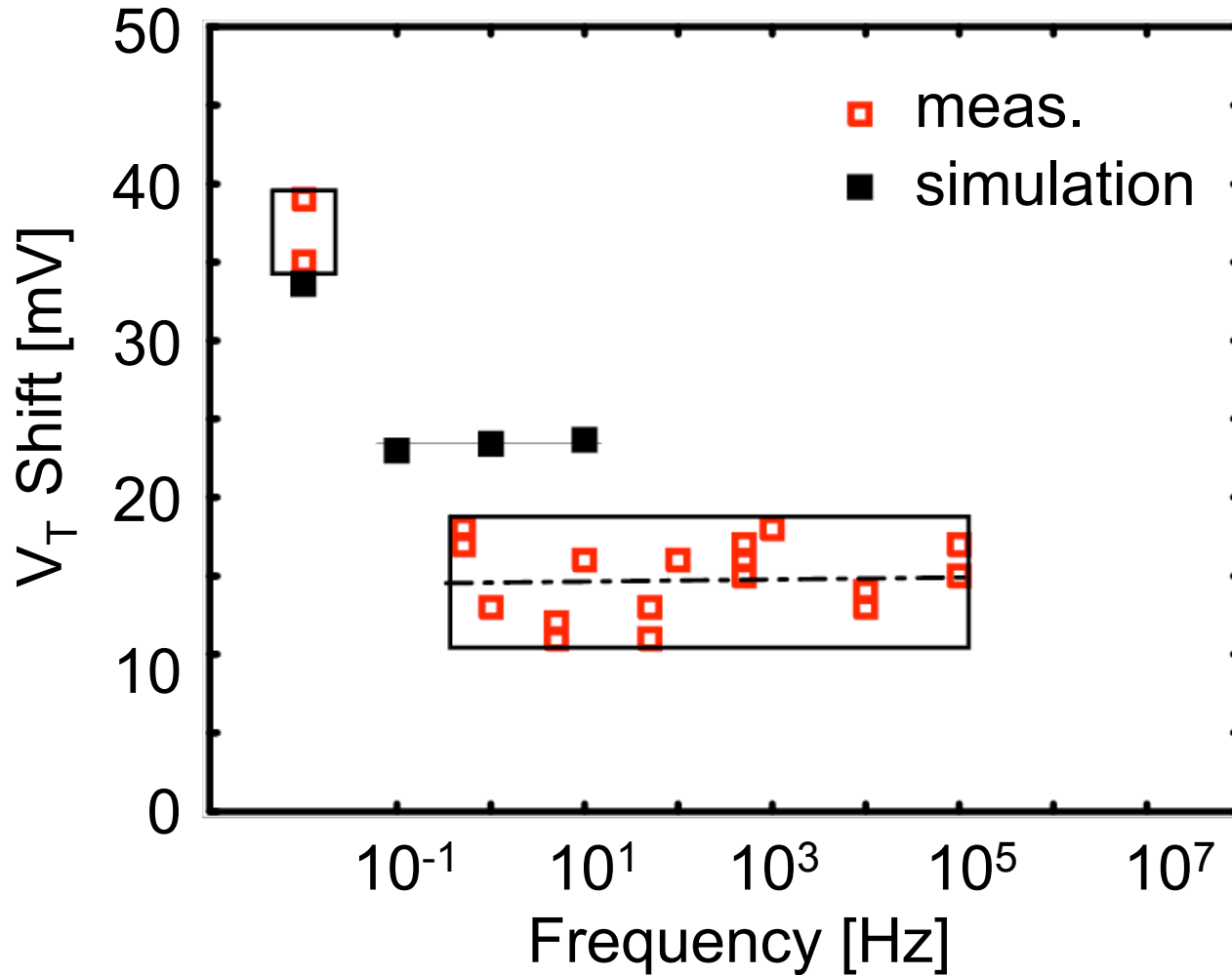


Approximate Analytical Models

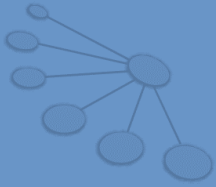




Frequency Dependence Interpreted

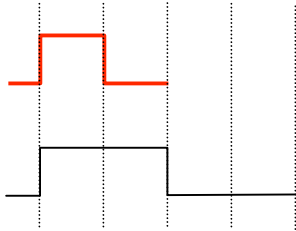


Symmetry in R-D model requires frequency-independent degradation

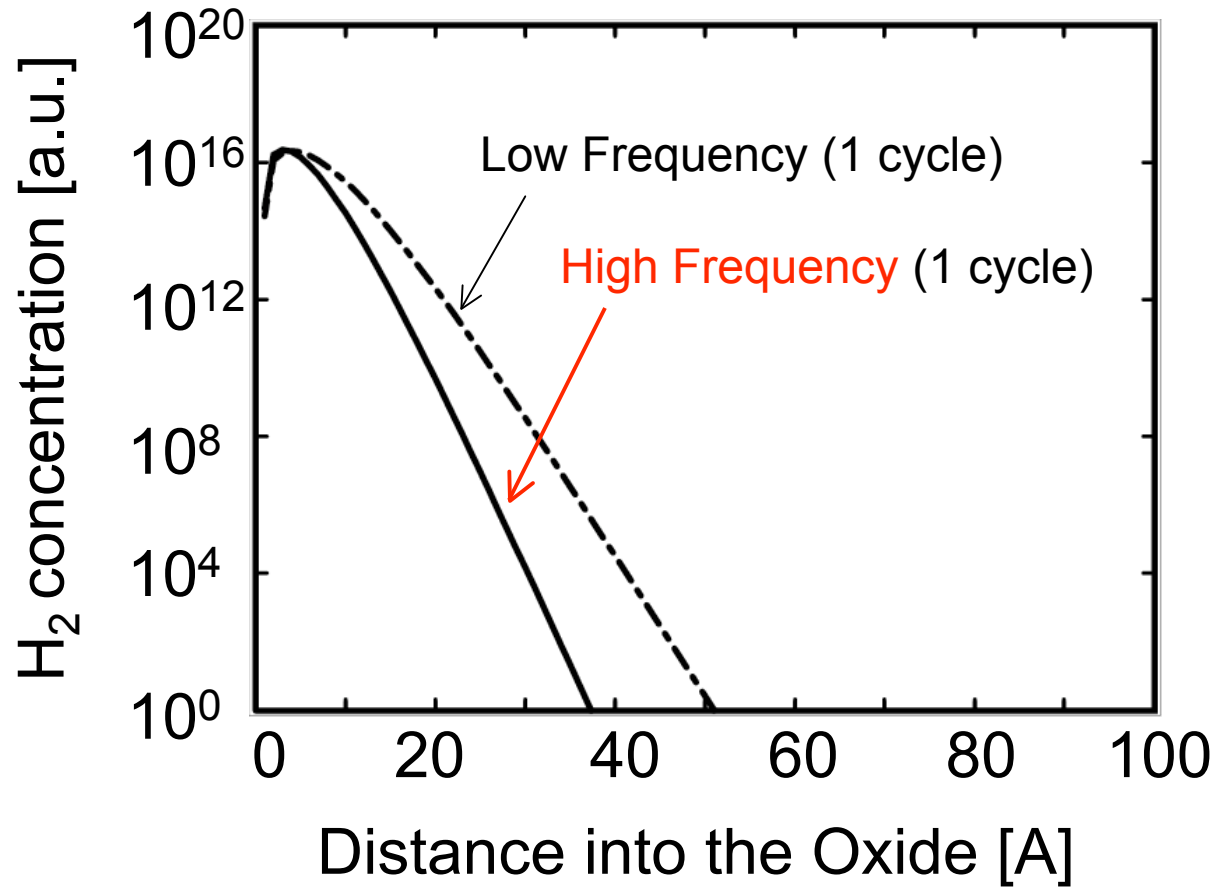
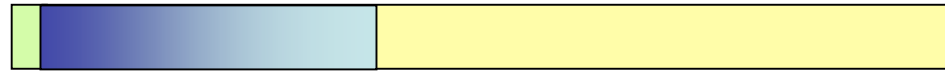
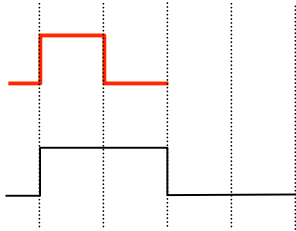


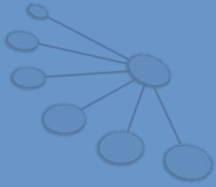
Frequency Independence Interpreted

High Freq



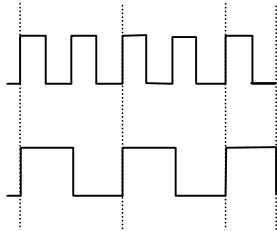
Low Freq



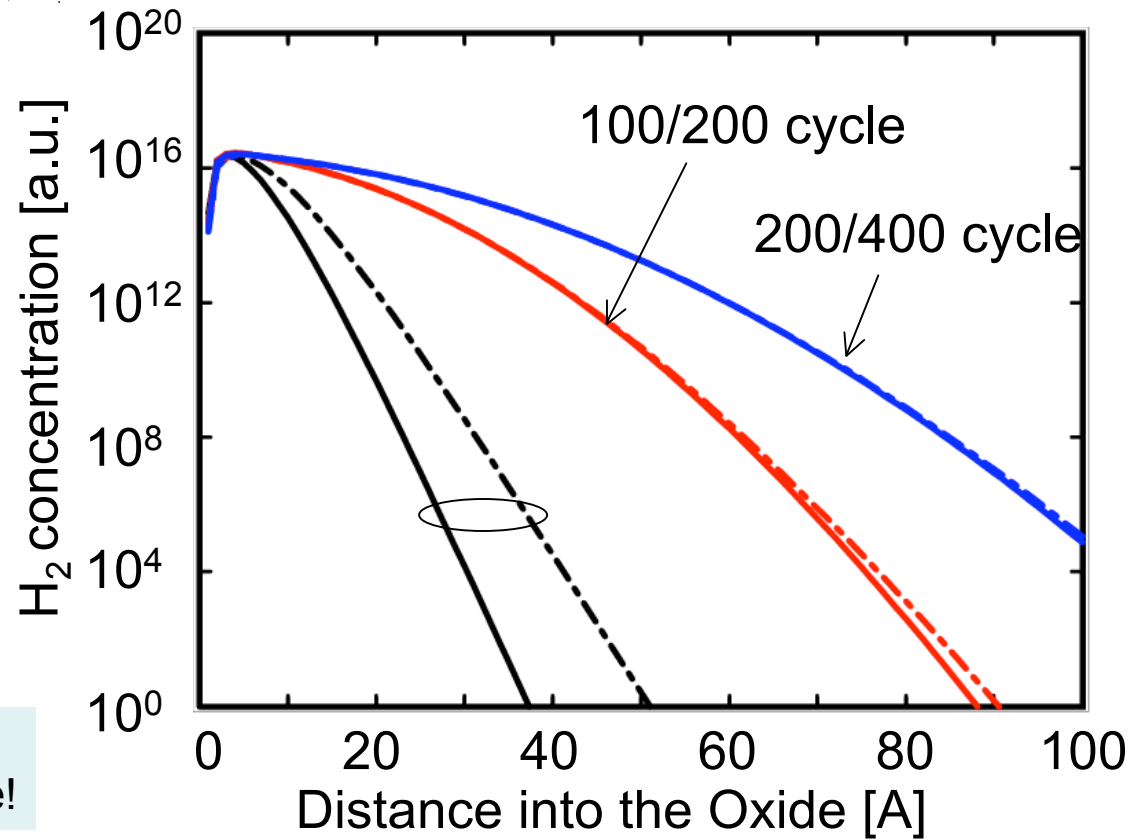


Frequency Independence Interpreted

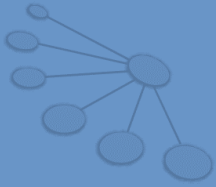
High Freq



Low Freq

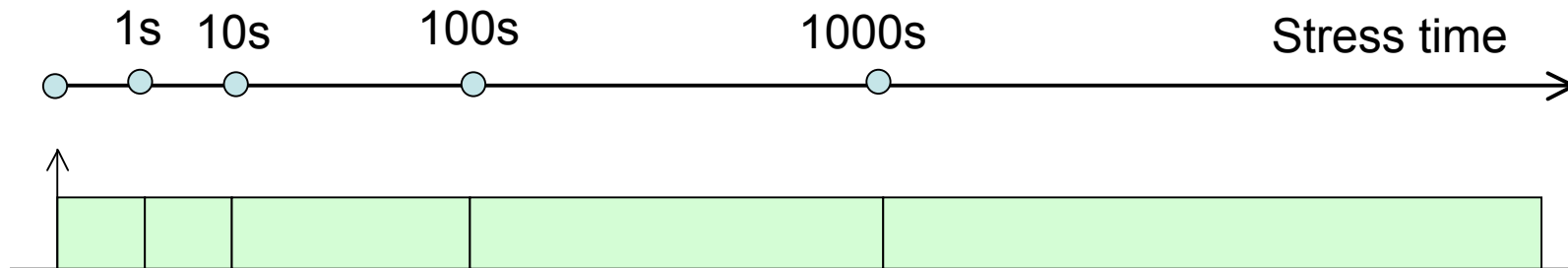


R-D model anticipates
Frequency Independence!

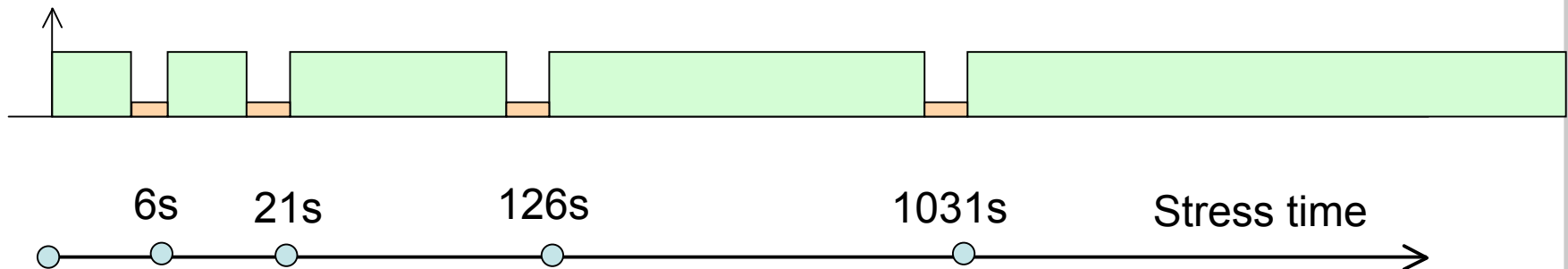


Measurement: A variable-frequency AC Stress!

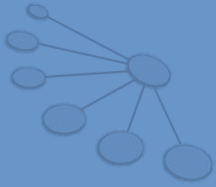
What we thought we were doing ...



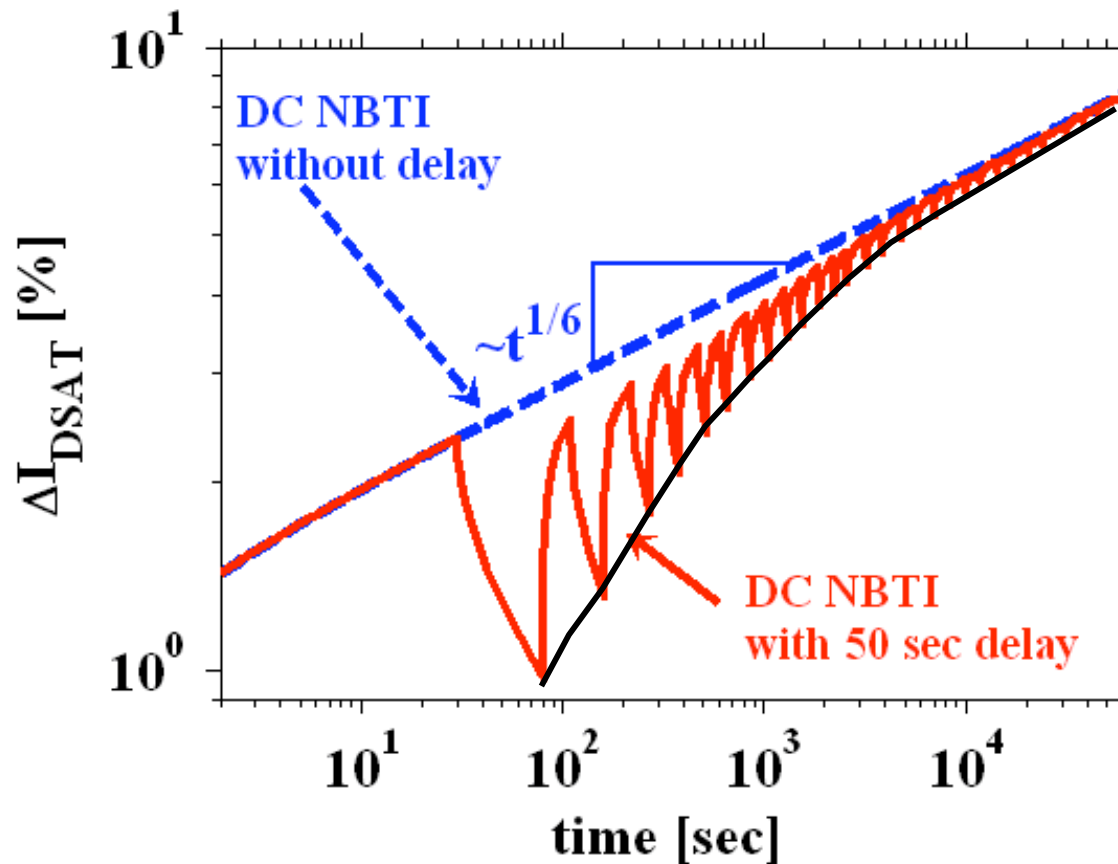
What we were actually doing ...



* 5 sec. measurement window (for example).

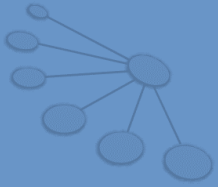


R-D Simulations for DC NBTI

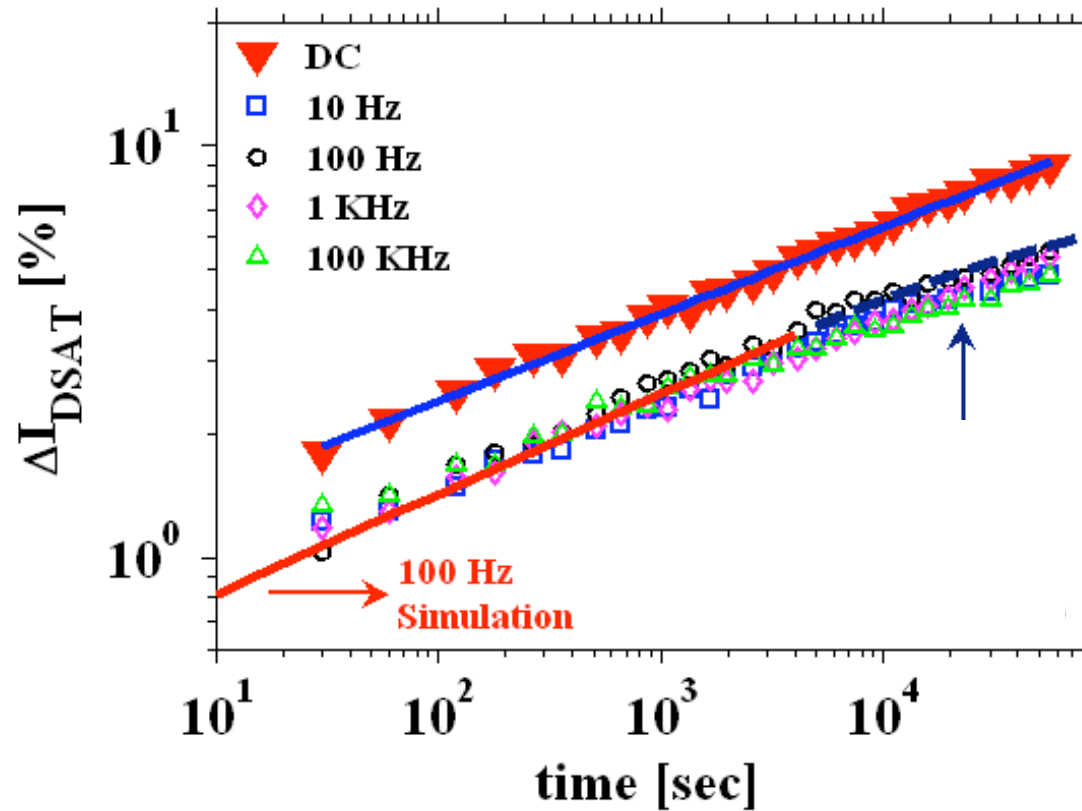


H. Kufloglu,
unpublished
results

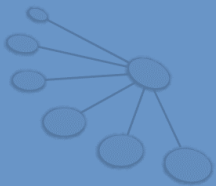
Actually, $n=0.16$ at all times (H2 diffusion), measurement delay makes it appear $n=0.25$ at short times. A 40 year old puzzle finally resolved!



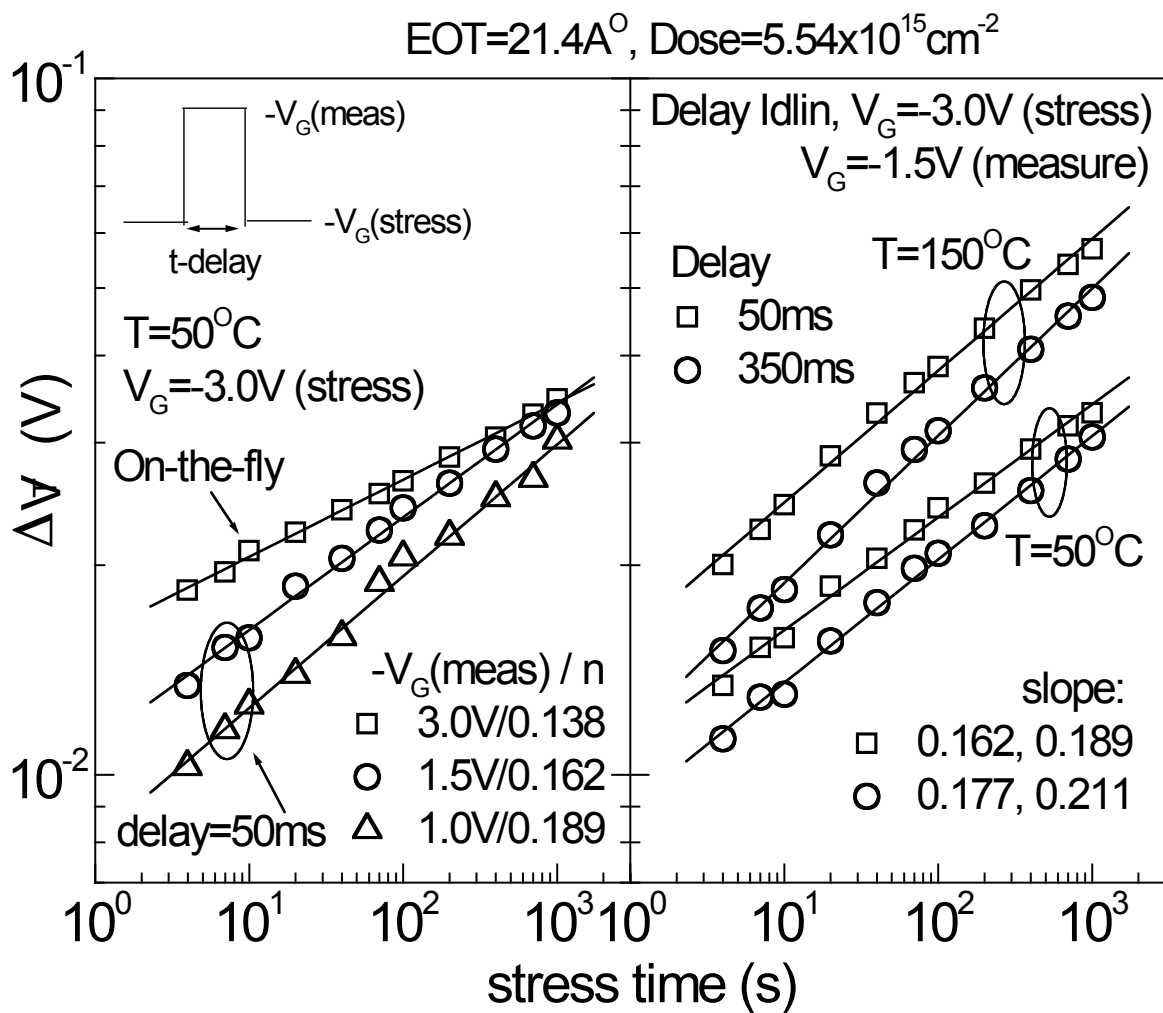
AC NBTI: Sim. & Measurement



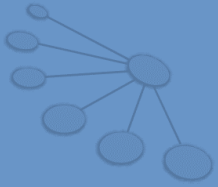
- Only DC simulations are fit to experimental data ($V_G=2.1V$).
- AC simulations are inherently related to DC results
- Delay of 6.3 sec is used



Conclusive Confirmation

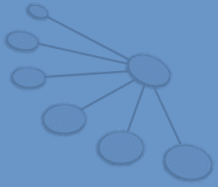


D. Varghese,
IEDM 2005



Conclusions

- Reliability is, has been, and will be a key consideration for a viable technology.
- Over the last fifteen years, reliability engineering (a collection of pragmatic, empirical rules) have gradually evolved into reliability physics (grounded in sound understanding of underlying physics).
- In this talk we considered NBTI, similar physical models exist for Hot carrier degradation and Time dependent dielectric breakdown.
- The NBTI model provides proper prescription of extrapolating device lifetime. We will consider these extrapolation methods in a separate talk.
- Finally, do not underestimate the power of simple models. What we did in 4/5 lines of algebra, is actually equivalent to tens of PRB, JAP, TED, EDL papers over last 30 years.



Collaboration and References

Experiments: S. Mahapatra, S. Kumar, D. Saha, D. Varghese, IIT

[1] Mahapatra and Alam, IEDM 2002, p. 505.

[2] Mahapatra, Kumar, & Alam, IEDM 2003, p. 337.

[3] Mahapatra et al. IEDM 2004, p. 105.

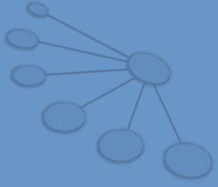
Theory: M. Alam, H. Kufluoglu, Purdue University

[1] Alam, Weir, & Silverman, IWGI 2001, p. 10.

[2] Alam, IEDM 2003, p. 346.

[3] Kufluoglu & Alam, IEDM 2004, p. 113.

- For convenience, most of the figures of this talk are taken from these references. I will use other figures to illustrate difference in opinions or to generalize results.



Questions & Answers